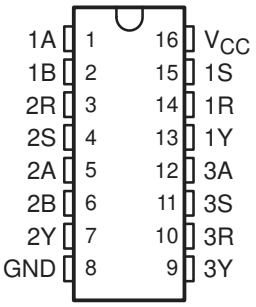
SLLS058B – SEPTEMBER 1973 – REVISED MAY 1995

- **Meets or Exceeds the Requirements of IBM™ System 360 Input/Output Interface Specification**
- **Operates From Single 5-V Supply**
- **TTL Compatible**
- **Built-In Input Threshold Hysteresis**
- **High Speed . . . Typical Propagation Delay Time = 20 ns**
- **Independent Channel Strobes**
- **Input Gating Increases Application Flexibility**
- **Designed for Use With Dual Line Driver SN75123**
- **Designed to Be Interchangeable With Signetics N8T24**

D OR N PACKAGE
(TOP VIEW)



description

The SN75124 triple line receiver is specifically designed to meet the input/output interface specifications for IBM System 360. It is also compatible with standard TTL logic and supply voltage levels.

The SN75124 has receiver inputs with built-in hysteresis to provide increased noise margin for single-ended systems. An open line affects the receiver input as does a low-level input voltage, and the receiver input can withstand a level of −0.15 V with power on or off. The other inputs are in TTL configuration. The S input must be high to enable the receiver input. Two of the line receivers have A and B inputs that, if both are high, hold the output low. The third receiver has only an A input that, if high, holds the output low.

See the SN751730 for new IBM 360/370 interface designs.

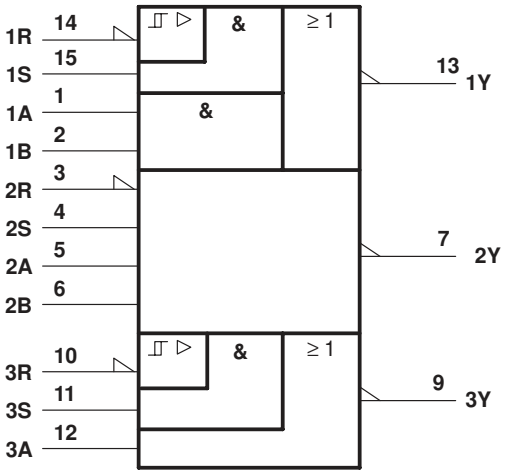
The SN75124 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

INPUTS				OUTPUT
A	B†	R	S	Y
H	H	X	X	L
X	X	L	H	L
L	X	H	X	H
L	X	X	L	H
X	L	H	X	H
X	L	X	L	H

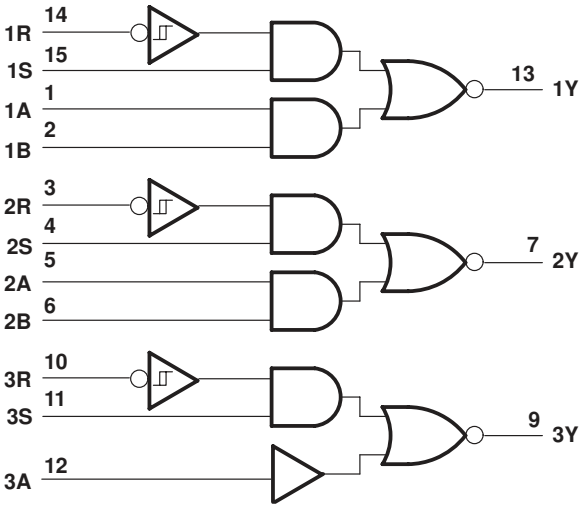
† B input and last two lines of the function table are applicable to receivers 1 and 2 only.

logic symbol†

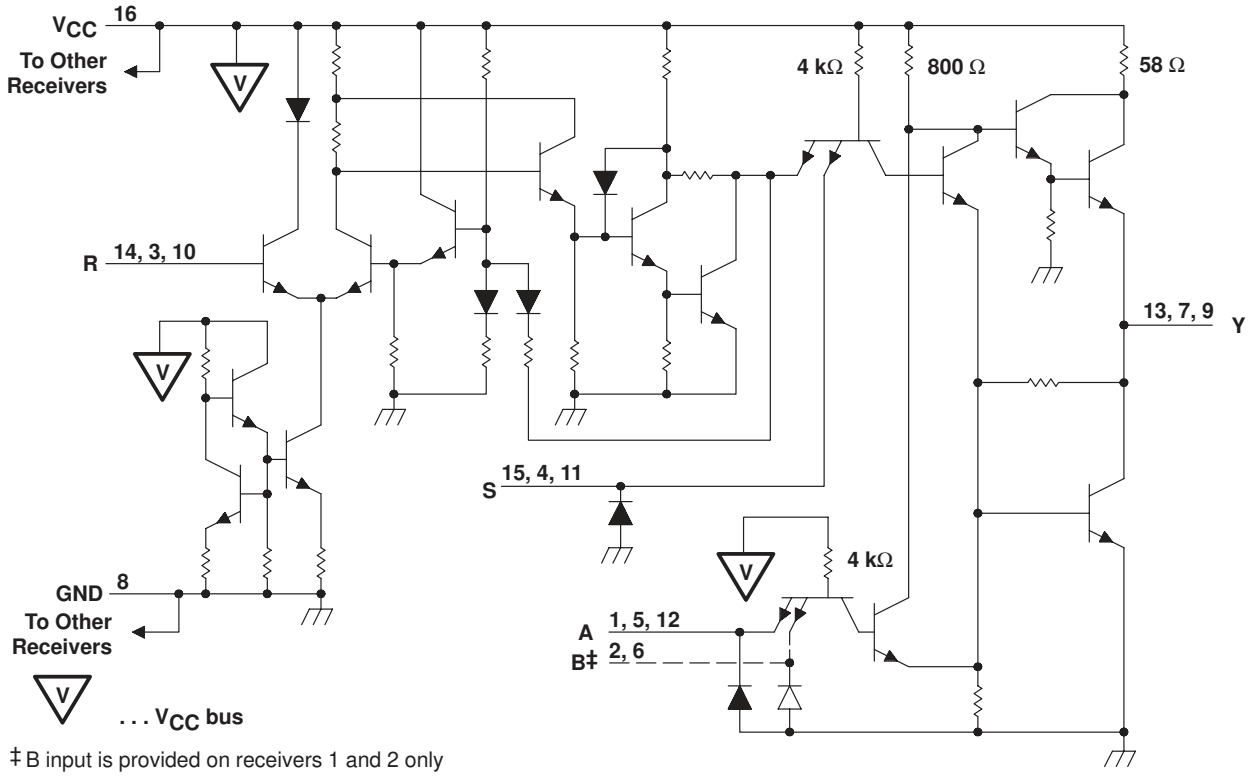


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



schematic (each receiver)



‡ B input is provided on receivers 1 and 2 only
Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage, V_I: R input with V_{CC} applied . . . . . 7 V
R input with V_{CC} not applied . . . . . 6 V
A, B, or S input . . . . . 5.5 V
Output voltage, V_O . . . . . 7 V
Output current, I_O . . . . . ±100 mA
Continuous total dissipation . . . . . See Dissipation Rating Table
Operating free-air temperature range, T_A . . . . . 0°C to 70°C
Storage temperature range, T_{stg} . . . . . −65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: Voltage values are with respect to network ground terminal

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING
D	950 mW	7.6 mW/°C	608 mW
N	1150 mW	9.2 mW/°C	736 mW

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.75	5	5.25	V
High-level input voltage, V_{IH}	A, B, or S	2			V
	R	1.7			
Low-level input voltage, V_{IL}	A, B, or S			0.8	V
	R			0.7	
High-level output current, I_{OH}				−800	μA
Low-level output current, I_{OL}				16	mA
Operating free-air temperature, T_A		0		70	°C

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER			TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{hys}	Hysteresis voltage ($V_{IT+} - V_{IT-}$)	R	V_{CC} = 5 V,	T_A = 25°C	0.2	0.5		V
V_{IK}	Input clamp voltage	A, B, or S	V_{CC} = 5 V,	I_I = −12 mA			−1.5	V
$V_{I(BR)}$	Input breakdown voltage	A, B, or S	V_{CC} = 5 V,	I_I = 10 mA	5.5			V
V_{OH}	High-level output voltage		$V_{IH} = V_{IH}$min, I_{OH} = −800 μA,	$V_{IL} = V_{IL}$max, See Note 2	2.6			V
V_{OL}	Low-level output voltage		$V_{IH} = V_{IH}$min, I_{OL} = 16 mA,	$V_{IL} = V_{IL}$max, See Note 2			0.4	V
I_I	Input current at maximum input voltage	R	V_I = 7 V				5	mA
			V_I = 6 V,	V_{CC} = 0			5	
I_{IH}	High-level input current	A, B, or S	V_I = 4.5 V				40	μA
		R	V_I = 3.11 V				170	
I_{IL}	Low-level input current	A, B, or S	V_I = 0.4 V,	V_{IR} = 0.8 V	−0.1		−1.6	mA
I_{OS}	Short-circuit output current†				−50		−100	mA
I_{CC}	Supply current		All inputs = 0.8 V				72	mA
			All inputs = 2 V				100	

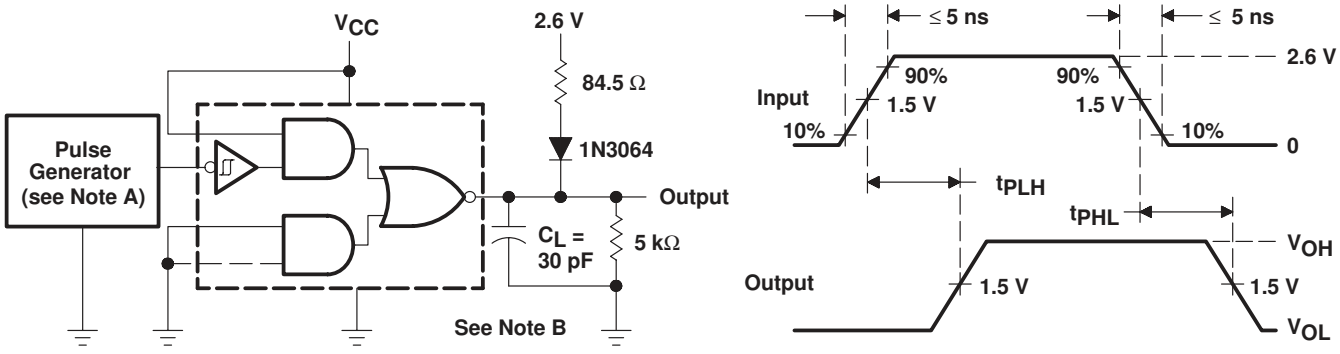
† Not more than one output should be shorted at a time, and duration of the short circuit should not exceed one second.

NOTE 2: The output voltage and current limits are characterized for any appropriate combination of high and low inputs specified by the function table for the desired output.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output from R input	See Figure 1		20	30	ns
t_{PHL}	Propagation delay time, high-to-low-level output from R input			20	30	

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT VOLTAGE WAVEFORMS

NOTES: A. The pulse generator has the following characteristics: $Z_O \approx 50\ \Omega$, PRR ≤ 5 MHz, duty cycle = 50%.
B. C_L includes probe and jig capacitance.

Figure 1. Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

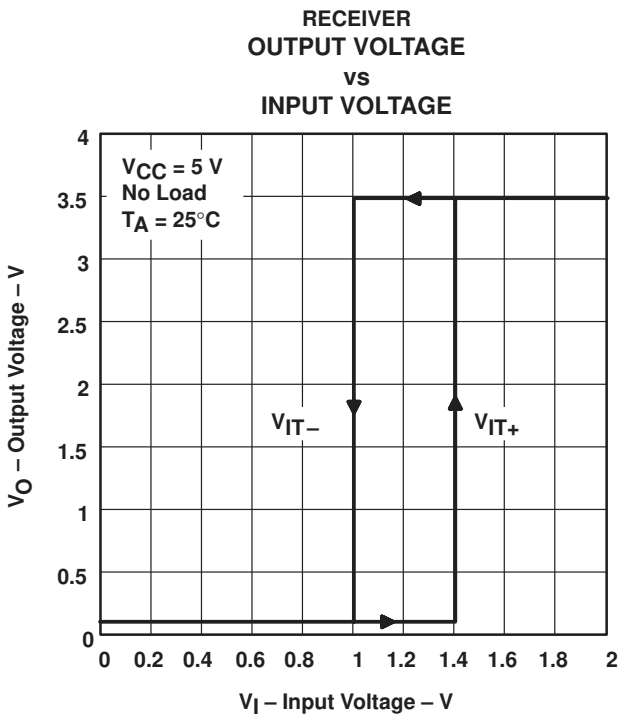


Figure 2

APPLICATION INFORMATION

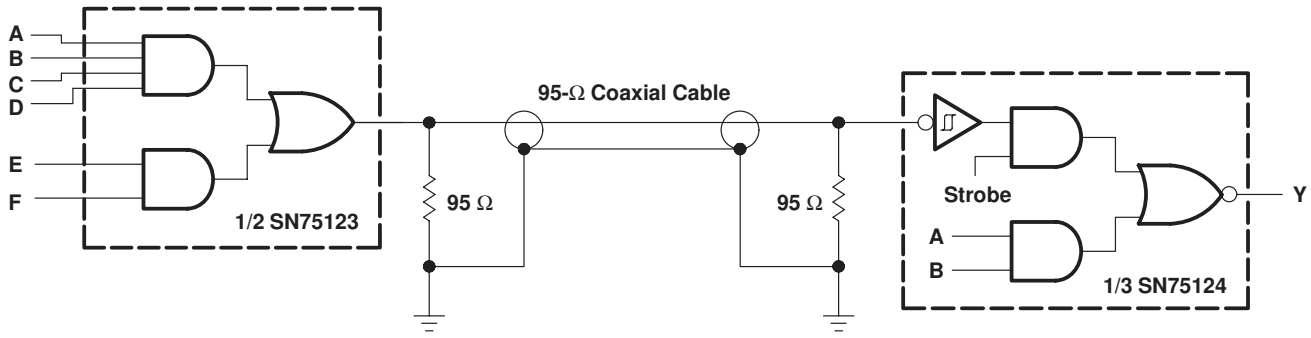


Figure 3. Unbalanced Line Communication Using SN75123 and SN75124

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN75124N	LIFEBUY	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75124N	
SN75124NSR	LIFEBUY	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75124	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

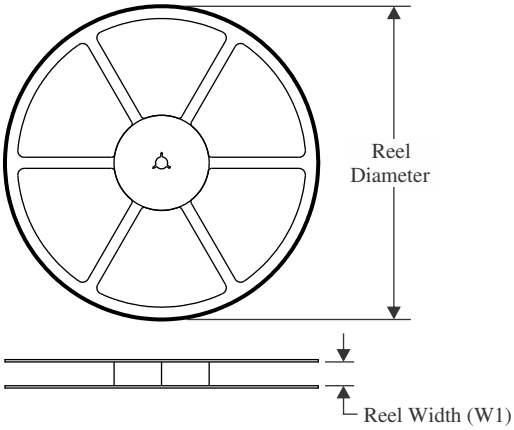
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

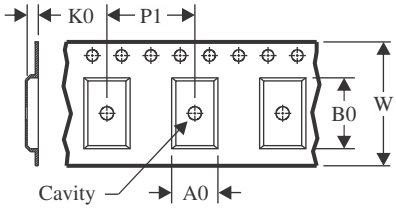
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

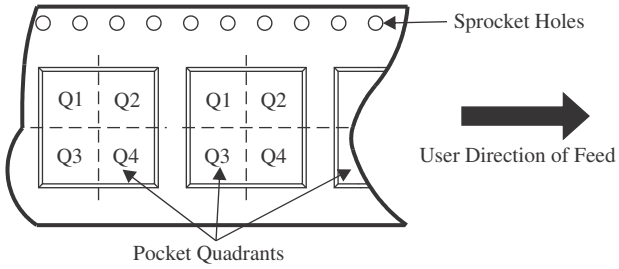


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

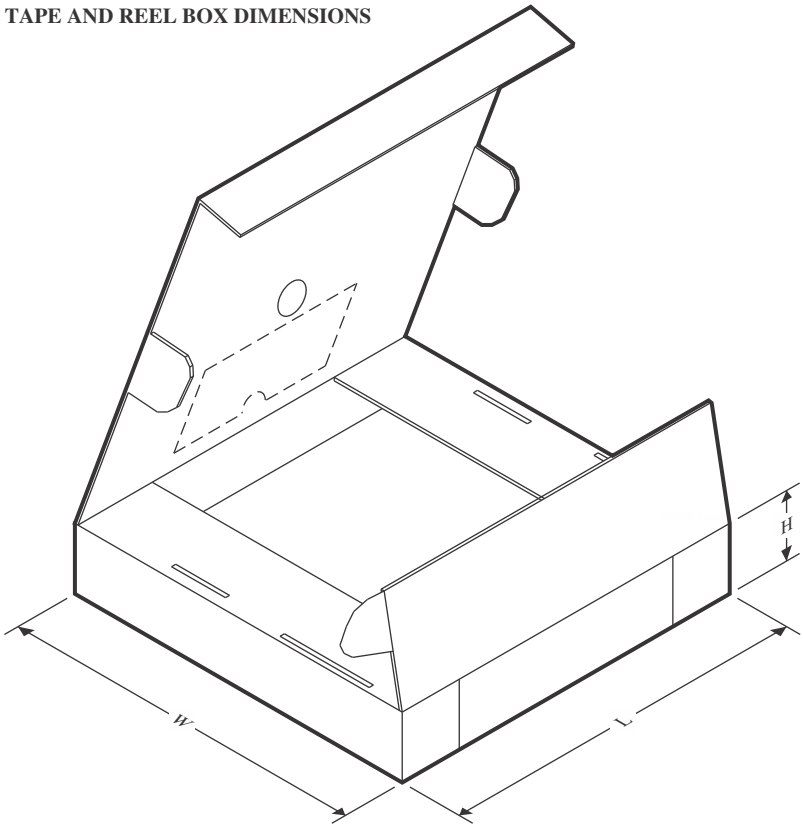
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75124NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

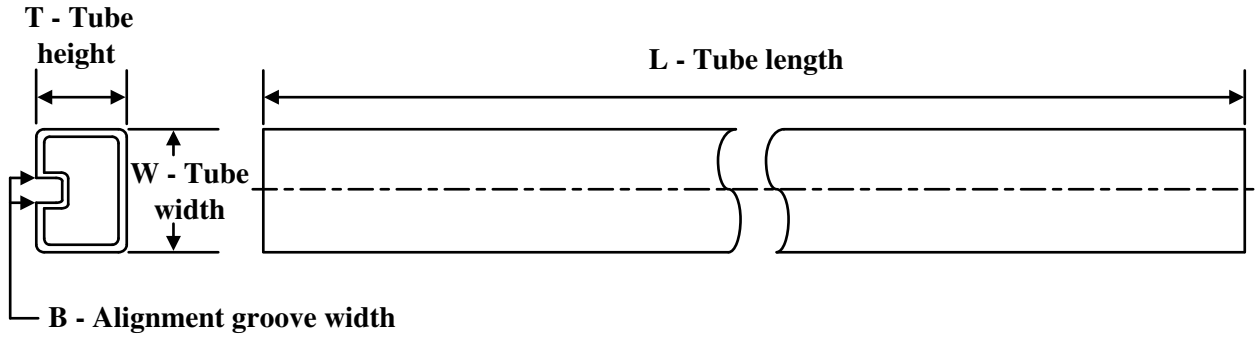
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

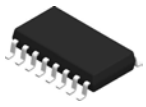
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75124NSR	SO	NS	16	2000	356.0	356.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN75124N	N	PDIP	16	25	506	13.97	11230	4.32

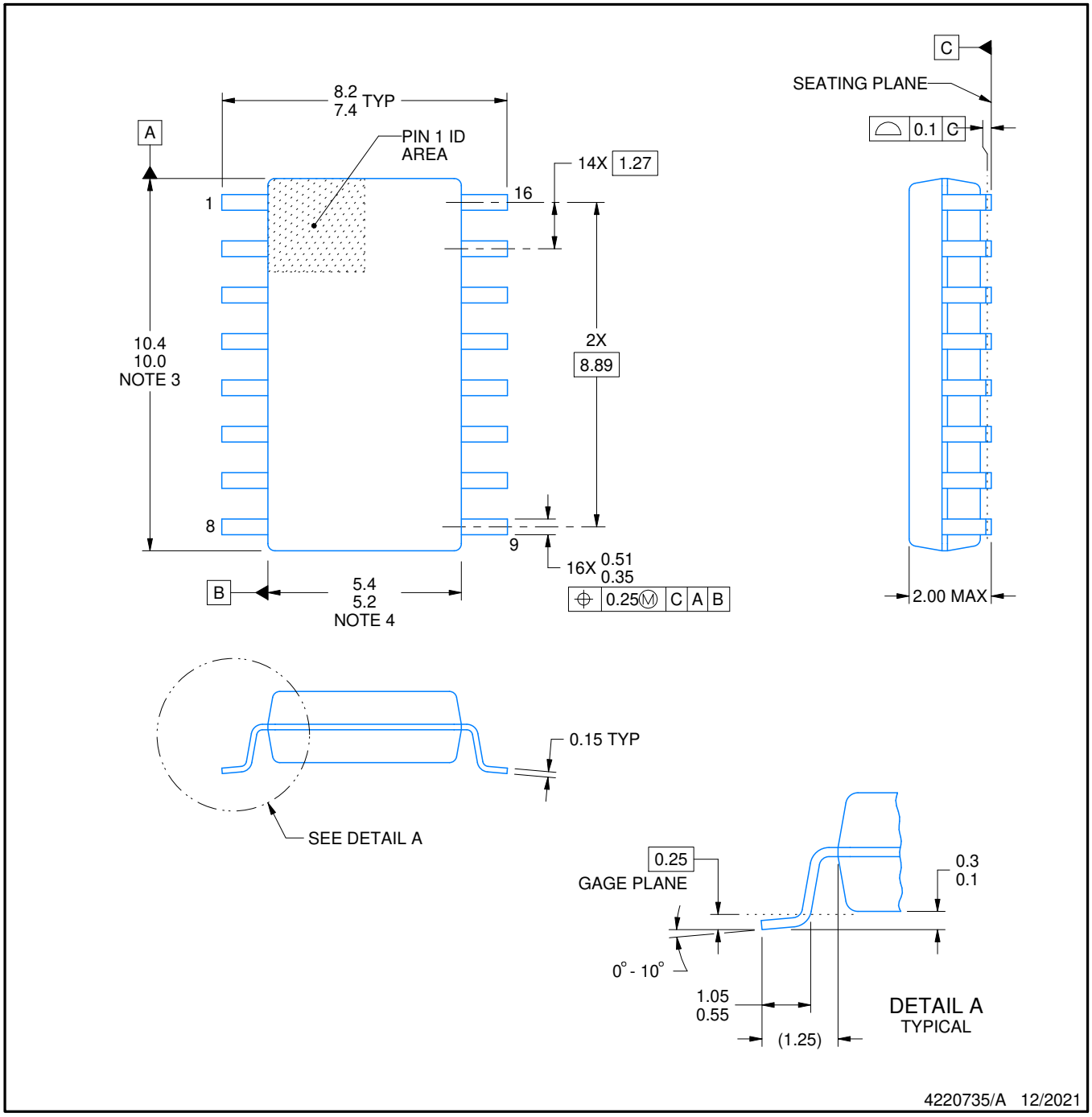


PACKAGE OUTLINE

NS0016A

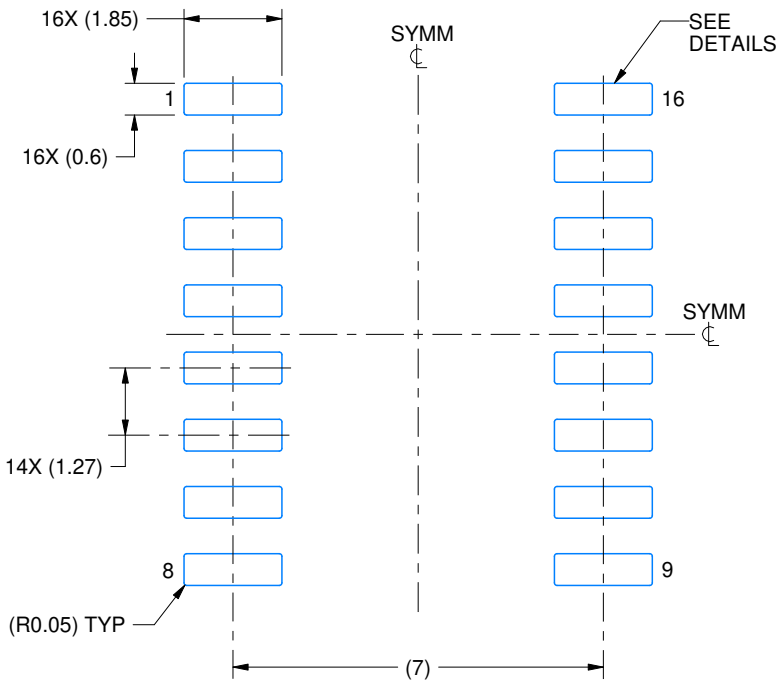
SOP - 2.00 mm max height

SOP

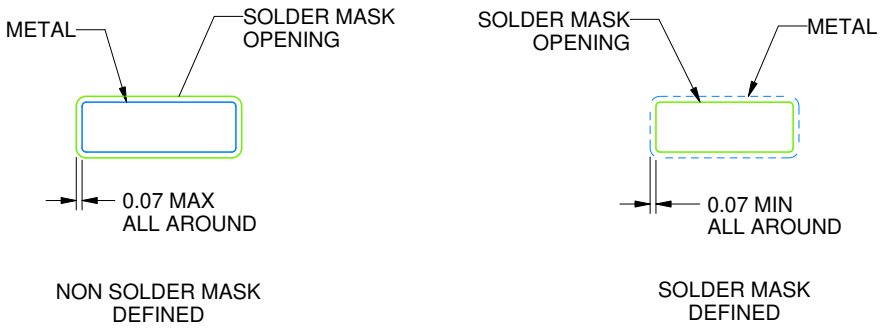


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



LAND PATTERN EXAMPLE
SCALE:7X

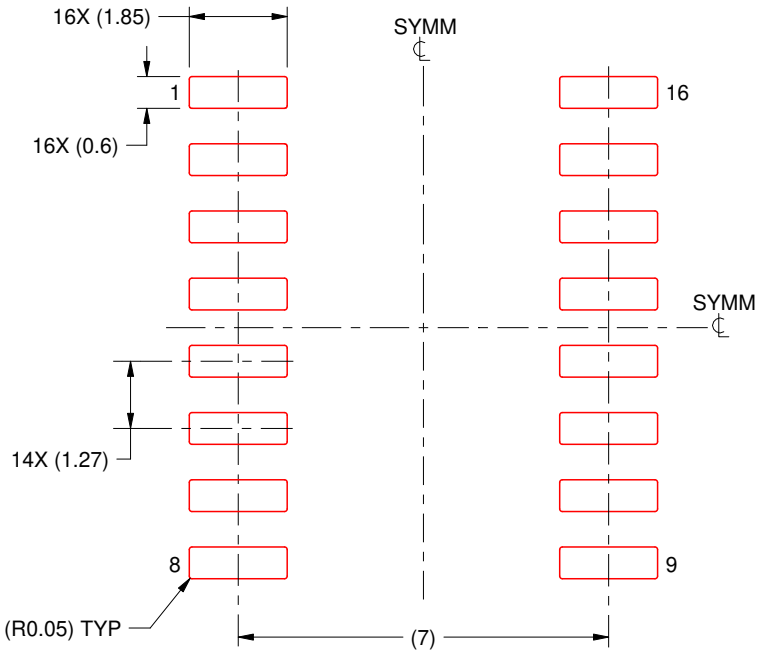


SOLDER MASK DETAILS

4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220735/A 12/2021

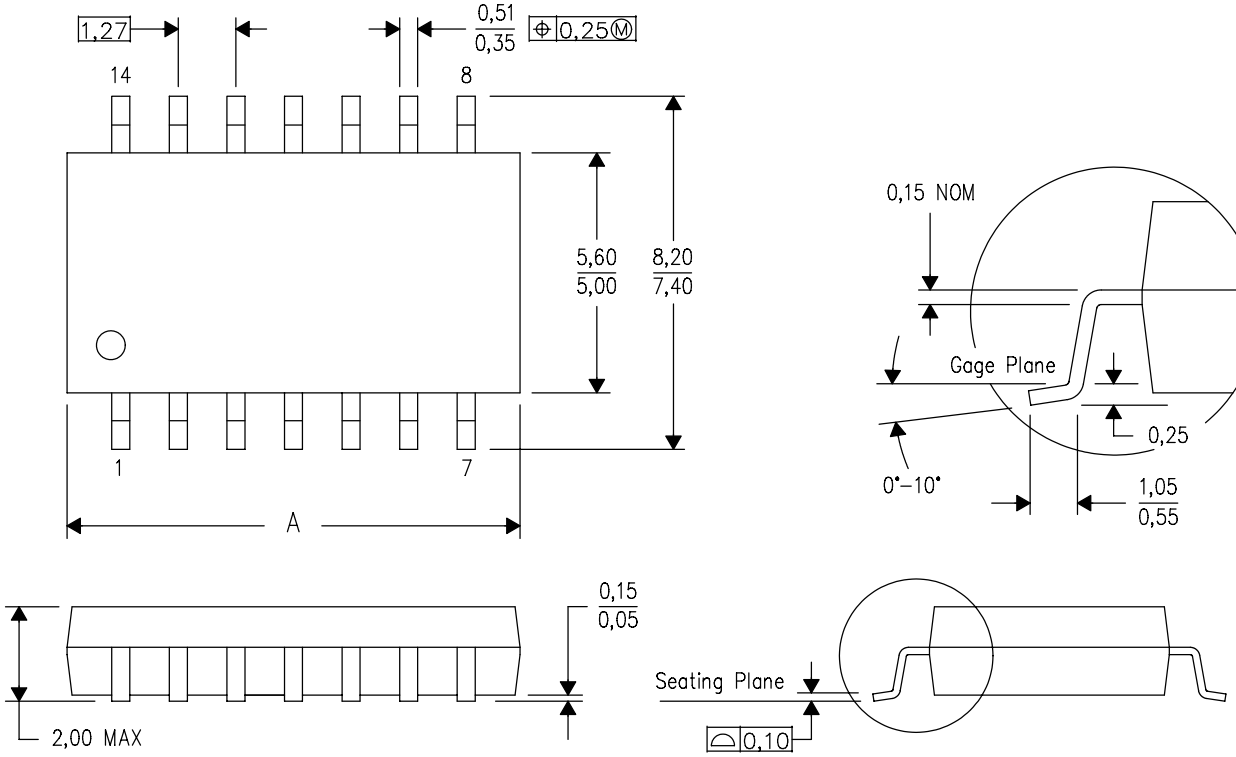
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

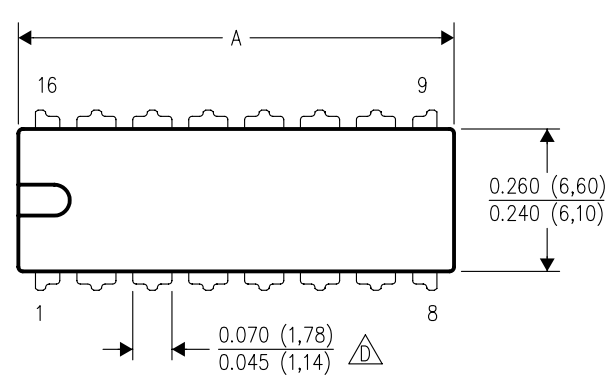
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

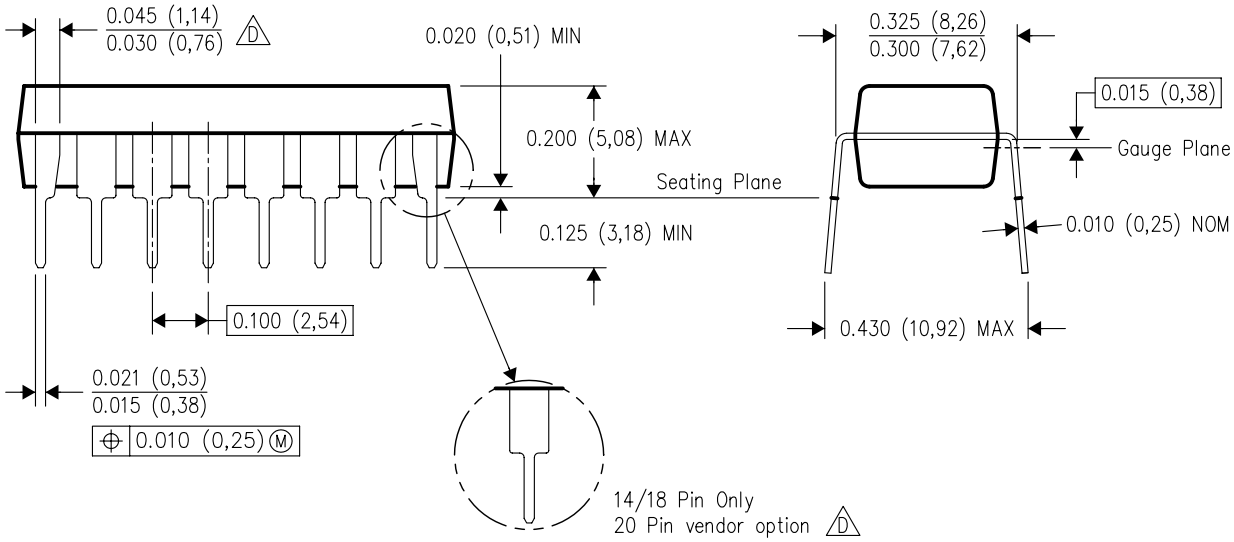
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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